

ABSTRACT

Provided is an ultrasonic inspection device 1 for inspecting a packaged semiconductor device D, The ultrasonic inspection device 1 including an ultrasonic transducer 2 that is disposed to face the semiconductor device D; a medium holding unit 12 that is provided at an end 2b of the ultrasonic transducer 2 facing the semiconductor device D and holds a medium M through which ultrasonic waves W are propagated; a stage 3 that moves the position of the semiconductor device D relative to the ultrasonic transducer 2; and an analysis unit 22 that analyzes the reaction of the semiconductor device D in accordance with input of the ultrasonic waves W from the ultrasonic transducer 2.

Figure 2